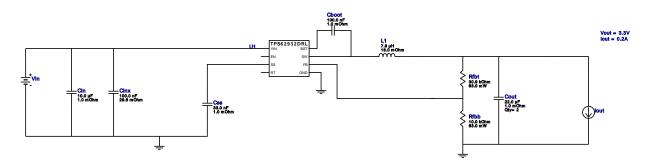
VinMin = 24.0V VinMax = 24.0V Vout = 3.3V Iout = 0.2A Device = TPS62932DRLR Topology = Buck Created = 2024-02-15 13:43:11.849 BOM Cost = \$0.92 BOM Count = 10 Total Pd = 0.09W

# WEBENCH® Design Report

Design: 4 TPS62932DRLR TPS62932DRLR 24V-24V to 3.30V @ 0.2A



#### **Electrical BOM**

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cboot	MuRata	GRM155R71A104KA01D Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	1	\$0.01	0402 3 mm <sup>2</sup>
Cin	TDK	C3216X5R1H106K160AB Series= X5R	Cap= 10.0 uF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 4.9 A	1	\$0.24	1206_180 11 mm <sup>2</sup>
Cinx	TDK	CGA3E2X7R1H104K080AA Series= X7R	Cap= 100.0 nF ESR= 29.6 mOhm VDC= 50.0 V IRMS= 971.99 mA	1	\$0.01	0603 5 mm <sup>2</sup>
Cout	MuRata	GRM188R60J226MEA0D Series= X5R	Cap= 22.0 uF ESR= 1.0 mOhm VDC= 6.3 V IRMS= 6.0 A	2	\$0.04	0603 5 mm <sup>2</sup>
Css	MuRata	GRM155R71A333KA01D Series= X7R	Cap= 33.0 nF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	1	\$0.01	0402 3 mm <sup>2</sup>
L1	NIC Components	NPI52P7R8MTRF	L= 7.8 μH 18.0 mOhm	1	\$0.36	
						IND_NPI52P 445 mm <sup>2</sup>
Rfbb	Vishay-Dale	CRCW040210K0FKED Series= CRCWe3	Res= 10.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm <sup>2</sup>
Rfbt	Vishay-Dale	CRCW040230K9FKED Series= CRCWe3	Res= 30.9 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm <sup>2</sup>
U1	Texas Instruments	TPS62932DRLR	Switcher	1	\$0.19	DRL0008A-MFG 9 mm <sup>2</sup>

### **Operating Values**

#	Name	Value	Category	Description
1.	Cin IRMS	112.653 mA	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	12.691 µW	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	239.792 mA	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	28.75 μW	Capacitor	Output capacitor power dissipation
	IC lpk	731.25 mA	IC	Peak switch current in IC
	•			
	IC Pd	83.341 mW	IC	IC power dissipation
	IC Tj	35.021 degC	IC	IC junction temperature
	IC Tolerance	16.0 mV	IC	IC Feedback Tolerance
9.	ICThetaJA Effective	60.25 degC/W	IC	Effective IC Junction-to-Ambient Thermal Resistance
10.	lin Avg	31.059 mA	IC	Average input current
11.	Ipp percentage	365.625 %	Inductor	Inductor ripple current percentage (with respect to average inductor current)
12.	L lpp	731.25 mA	Inductor	Peak-to-peak inductor ripple current
	L Pd	1.755 mW	Inductor	Inductor power dissipation
	Cin Pd	12.691 µW	Power	Input capacitor power dissipation
	Cout Pd	28.75 μW	Power	Output capacitor power dissipation
	IC Pd	•		
		83.341 mW	Power	IC power dissipation
	L Pd	1.755 mW	Power	Inductor power dissipation
	Total Pd	85.402 mW	Power	Total Power Dissipation
19.	BOM Count	10	System	Total Design BOM count
			Information	
20.	Duty Cycle	7.547 %	System	Duty cycle
			Information	• •
21.	Efficiency	88.543 %	System	Steady state efficiency
	,		Information	,,
22	FootPrint	400.02		Total Foot Brint Area of BOM components
22.	FOOLPTINE	490.0 mm <sup>2</sup>	System	Total Foot Print Area of BOM components
	_		Information	
23.	Frequency	273.626 kHz	System	Switching frequency
			Information	
24.	Inductor ripple current	40.0 %	System	Custom Inductor ripple current (% of average inductor current)
	requirement used for		Information	requirement used for Inductor selection
	Inductor selection			1
25.	lout	200.0 mA	System	lout operating point
25.	lout	200.0 IIIA	•	lout operating point
		14000	Information	
26.	lout transient step used	1100.0 mA	System	Custom Transient current step requirement that was used for Cout
	for Cout calculations		Information	selection (A).
27.	Mode	PFM	System	Conduction Mode
			Information	
28.	Overshoot Value	748.636 µV	System	Theoretical Vout Overshoot Value
			Information	
20	Pout	660.0 mW		Total output power
<b>2</b> 3.	i out	660.0 mW	System	i otal output powel
00	T-1-I DOM	<b>#0.00</b>	Information	TuelBOMOssi
30.	Total BOM	\$0.92	System	Total BOM Cost
			Information	
31.	Undershoot Value	20.087 mV	System	Theoretical Vout Undershoot Value
			Information	
32.	Vin	24.0 V	System	Vin operating point
J <u>_</u> .	•	,	Information	· · · · · · · · · · · · · · · · · · ·
22	Vin n n	25 020 m\/		Dook to pook input voltage
33.	Vin p-p	35.039 mV	System	Peak-to-peak input voltage
			Information	
34.	Vout	3.3 V	System	Operational Output Voltage
			Information	
35.	Vout Actual	3.272 V	System	Vout Actual calculated based on selected voltage divider resistors
			Information	ŭ
36.	Vout Ripple	1.0 %	System	Custom maximum output ripple requirement that was used for Cout
JU.	requirement used for	70	Information	selection(% of Vout).
	•		inionnation	Solodion (70 Or Vout).
o <del>-</del>	Cout calculations	0.557.67	0	Mod Tolomore board a 10 T land of the control of th
37.	Vout Tolerance	3.557 %	System	Vout Tolerance based on IC Tolerance (no load) and voltage divide
			Information	resistors if applicable
38.	Vout p-p	24.803 mV	System	Peak-to-peak output ripple voltage
			Information	
39.	Vout transient	3.0 %	System	Custom Transient voltage change requirement that was used for Co
JJ.		0.0 /0	Information	selection (% of Vout).
	requirement used for			
	requirement used for Cout calculations		IIIIOIIIIalioii	Selection (70 or vout).

## **Design Inputs**

Name	Value	Description	
lout	200.0 m	Maximum Output Current	
VinMax	24.0	Maximum input voltage	
VinMin	24.0	Minimum input voltage	
Vout	3.3	Output Voltage	
base_pn	TPS62932	Base Product Number	
source	DC	Input Source Type	
Та	30.0	Ambient temperature	

### WEBENCH® Assembly

#### Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

#### Soldering Component to Board

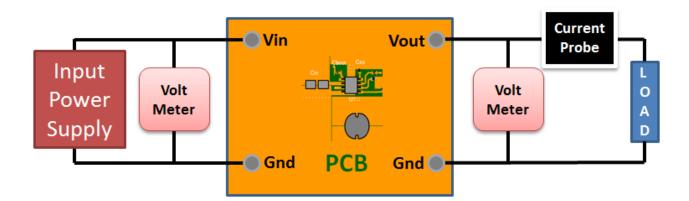
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

#### Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 24.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum lout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

#### Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.

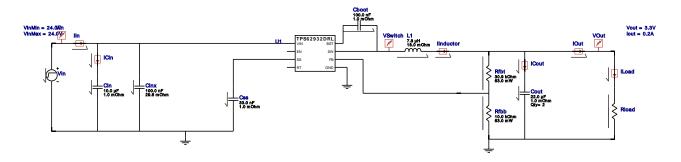


# **WEBENCH**<sup>®</sup> Electrical Simulation Report

Design Id = 4

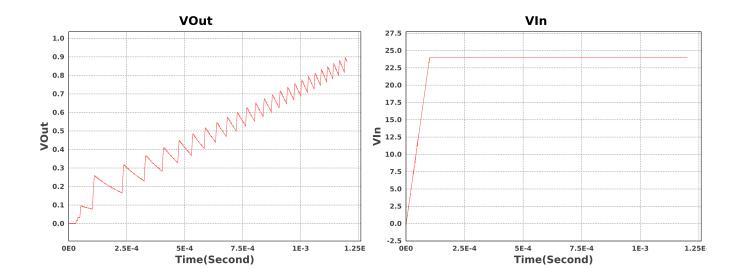
sim\_id = 1

Simulation Type = Startup



#### Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	Cout	IC	Initial Voltage	0 V
2	Rload	R	Load Resistance	16 49999999999996 ohm



### Design Assistance

- 1. Master key: 37C3C50233B7D137384961381C9450C6[v1]
- 2. **TPS62932** Product Folder: http://www.ti.com/product/TPS62932: contains the data sheet and other resources.

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